

CHANGE NOTIFICATION

ISSUE DATE: 17-MAR-16
Attn: DIGI-KEY CORPORATION
Subject: PRODUCT AND PROCESS CHANGE NOTIFICATION
Notification: 17032
Title: MC9S12ZVC 64LQFP-EP Mold Compound and Lead Frame with 280um Wafer Thickness Qualification in NXP-ATTJ
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Notification Summary:

NXP announces the conversion of molding compound, lead frame and die thickness for the MC9S12ZVC on 64LQFP-EP products assembled at NXP-ATTJ assembly site, Tianjin, China. MC9S12ZVC using a molding compound Hitachi CEL9200HF10M-CW will be standardized to Hitachi CEL9240HF16FL, lead frame flag siz...

Dear Customer,

NXP has sent this automated email to inform you of the change noted above. **Please go to www.nxp.com to view the entire customer copy of this change notification.** To provide specific conditions of acceptance, request further data, or request a customer copy, please enter a Support Case. Be aware that after you select this link to enter your request, you must choose the topic "Product Change Notification" once on the Salesforce page.

You can not reply to this email.

DISCLAIMER:

NXP will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis.

Regards,
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